



Volume 13, Issue 1



#### **From the Director's Desk**

James Amano, Senior Director

#### ***Equipment Data Acquisition and Smart Manufacturing***

Manufacturers are increasingly adopting the SEMI Equipment Data Acquisition (EDA) suite of standards. [Read More](#)

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#### **Japan Standards Awards**

SEMI honored industry leaders for their outstanding accomplishments in developing Standards for the electronics and related industries. [Read More](#)

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#### **Korea Standards Awards**

Three members of the Korea FPD Metrology TC Chapter received the SEMI Recognition Award. [Read More](#)

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#### **China SEMI HB-LED Update—December 2017**

Although the industry faces challenges, critical SEMI Standards development efforts continue. [Read More](#)

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#### **New Standard, Specification for Reference Material for Bonded Wafer Stack Void Metrology**

SEMI 3D17 describes test structures, including design, manufacturing, and certification procedure for a bonded wafer reference sample composed of two wafers. [Read More](#)

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#### **New Standard, Specification of Indoor Lighting Simulator Requirements for Emerging Photovoltaic**

Testing equipment for evaluation of emerging PV technologies is increasingly necessary. [Read More](#)

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### **Next-Generation SEMI Equipment Data Acquisition (EDA) Standards**

The microelectronics supply chain is seeking standardized data collection and automation strategies for big data transfers. [Read More](#)

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### **SEMI forms Technology Communities**

SEMI forms Technology Communities to speed industry collaboration and innovation. [Read More](#)

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### **Standards Calendar**

March 14-16	<a href="#">SEMICON China 2018</a>
April 9-12	<a href="#">North America Standards Spring 2018 Meetings</a>

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